



Final Product Change Notification

201608014F01W

Issue Date: 07-Sep-2018

Effective Date: 05-Dec-2018

WITHDRAWAL

Dear *Tracy Hoglin*,

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Management Summary

This is a withdrawal of the Cu Wire Qualification related FPCNs for PLCC44/52/68/84, including former Freescale PCN 16960 and FPCN 201608014F01.

Change Category

- | | | | | |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test Location | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Process | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer Fab Location | <input checked="" type="checkbox"/> Assembly Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

FPCN Withdrawal: 1.2um IDR PLCC 44/52/68/84 Cu Wire Qualification in Amkor Technology Philippines ATP1

Description of Change

This is withdrawal notification for the change described below. See the Withdrawal Information section for further details.

NXP Semiconductor announces the assembly site transfer for the parts with PLCC44/52/68 packages listed in this notification from the current NXP-ATKL, Kuala Lumpur, Malaysia, assembly Facility to the Subcon Amkor Technology Philippines (ATP1), Muntinlupa, Philippines Facility with Cu wire conversion.

NXP Semiconductor announces the addition of Copper Wire as a wire bond material for the products with PLCC84 package that are currently assembled in Amkor Technology Philippines (ATP1).

For more detailed information, please refer to attachment.

Reason for Change

Qualification of Subcon Amkor Technology Philippines (ATP1), Muntinlupa, Philippines Assembly Facility is to ensure customer supply assurance.

The conversion from Gold to Copper wire is required to mitigate against raw material cost increases and for supply assurance.

Identification of Affected Products

Top side marking

For PLCC44/52/68, the current assembly site marking is (QQ) for NXP Semiconductor Kuala Lumpur assembly site and will change to (ZR) for the Subcon Amkor Technology Philippines (ATP1).

Product Availability

Sample Information

Samples are available from 10-Sep-2016

Below samples are available from 10-Sep-2016.

KC711E20MFNE2, package PLCC52;

KC11F1VFNE3, package PLCC68;

KC711K4VFNE4, package PLCC84.

Production

Planned first shipment 21-Nov-2016

Withdrawal Information

1. Withdrawal of Cu Wire Qualification related FPCNs for PLCC44/52/68/84, includes F-FSL PCN 16960 and FPCN 201608014F01. FPCN 201608014F01 is lead frame information correction for F-FSL PCN16960.

2. Due to issues related to Cu Wire capable molding compound for PLCC44/52/68/84, high volume manufacturing cannot be supported. So Cu wire will not be used in Amkor Technology Philippines (ATP1), Muntinlupa, Philippines assembly facility.

3. There has never been any Cu wire production shipment from Amkor Technology Philippines (ATP1), Muntinlupa, Philippines assembly facility.

4. New PCN 201803025F01 for Au wire transfer from NXP-ATKL to ATP1 was distributed. In the future, only Au wire material from Amkor Technology Philippines (ATP1), Muntinlupa, Philippines assembly facility will be shipped.

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Disposition of Old Products

There has never been any Cu wire production shipment from Amkor Technology Philippines (ATP1), Muntinlupa, Philippines assembly facility.

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 07-Oct-2018.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Position Product Engineer
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Customer Focus, Passion to Win.

NXP Quality Management Team.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
S711E20E0VFNE2	935317461574	S711E20E0VFNE2	8BIT, 20K EPROM, 768RAM,	SOT238-4	PLCC52	RFS	BL Microcontrollers
MC68HC705C8ACFNE	935322581574	MC68HC705C8ACFNE	HC05 CORE + 8K RAM + EPR	SOT187-3	PLCC44	RFS	BL Microcontrollers